

English Version

**Printed board assemblies - Part 2: Sectional specification -
Requirements for surface mount soldered assemblies
(IEC 61191-2:2017/COR1:2019)**

Ensembles de cartes imprimées - Partie 2: Spécification
intermédiaire - Exigences relatives à l'assemblage par
brasage pour montage en surface
(IEC 61191-2:2017/COR1:2019)

Elektronikaufbauten auf Leiterplatten - Teil 2:
Rahmenspezifikation - Anforderungen an gelötete
Baugruppen in Oberflächenmontage
(IEC 61191-2:2017/COR1:2019)

This corrigendum becomes effective on 25 October 2019 for incorporation in the English language version of the EN.



European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

Endorsement notice

The text of the corrigendum IEC 61191-2:2017/COR1:2019 was approved by CENELEC as EN 61191-2:2017/AC:2019-10 without any modification.

INTERNATIONAL ELECTROTECHNICAL COMMISSION

IEC 61191-2
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PRINTED BOARD ASSEMBLIES –

**Part 2: Sectional specification –
Requirements for surface mount soldered assemblies**

C O R R I G E N D U M 1

Figure 5 – J lead joint

Replace, in the table, footnote f by footnote d, and delete footnote e.